

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT8094317

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
BO-FENG YOUNG	02/18/2020
CHUNG-TE LIN	02/18/2020
SAI-HOOI YEONG	02/18/2020
YU-MING LIN	02/27/2020
SHENG-CHIH LAI	02/27/2020
CHIH-YU CHANG	02/18/2020
HAN-JONG CHIA	02/19/2020
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD. 6
Internal Address:	HSIN-CHU SCIENCE PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	18364616
CORRESPONDENCE DATA	
Fax Number:	(216)502-0601
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	2165020600
Email:	DOCKETING@EPIPLAW.COM
Correspondent Name:	ESCHWEILER & POTASHNIK
Address Line 1:	195 S. MAIN ST., SUITE 400
Address Line 4:	AKRON, OHIO 44308
ATTORNEY DOCKET NUMBER:	TSMCP1120USB
NAME OF SUBMITTER:	DENISE A. HUSPASKA
SIGNATURE:	/Denise A. Huspaska/

DATE SIGNED:	08/03/2023
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Total Attachments: 9

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PATENT ASSIGNMENT

PARTIES TO THE ASSIGNMENT

Assignor(s):
Bo-Feng Young

Assignor(s):
Chung-Te Lin

Assignor(s):
Sai-Hooi Yeong

Assignor(s):
Yu-Ming Lin

Assignor(s):
Sheng-Chih Lai

Assignor(s):
Chih-Yu Chang

Assignor(s):
Han-Jong Chia

Assignee:
Taiwan Semiconductor Manufacturing Co., Ltd.
No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park
Hsin-Chu, Taiwan 300-77
Republic of China

AGREEMENT

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled
"EMBEDDED FERROELECTRIC FINFET MEMORY DEVICE" for which:

a non-provisional application for United States Letters Patent:

was executed on even date preparatory to filing (each inventor should sign this
Assignment on the same day as he/she signs the Declaration); or

was filed on _____ and accorded U.S. Serial No. _____; or

I hereby authorize and request my attorney associated with Customer No. 107476, to insert on the designated lines below the filing date and application number of said application when known:

U.S. Serial No. _____

filed on _____

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for

United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

2020.02.18
Date

楊柏榮
Name: 1st Inventor Bo-Feng Young

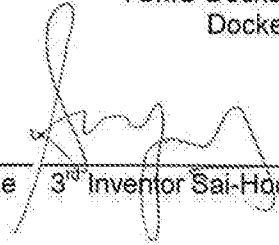
TSMC Docket No. P20191274US00
Docket No. TSMCP1120US

7/16/2020
Date


Name: 2nd Inventor Chung-Te Lin


TSMC Docket No. P20191274US00
Docket No. TSMCP1120US

2/18/2022
Date


Name 3rd Inventor Sai-Hoai Yeong

TSMC Docket No. P20191274US00
Docket No. TSMCP1120US

3/7/2020
Date


Name, 4th Inventor Yu-Ming Lin

TSMC Docket No. P20191274US00
Docket No. TSMCP1120US

Feb 27th, 2020
Date

Sheng-Chih Lai
Name 5th Inventor Sheng-Chih Lai

TSMC Docket No. P20191274US00
Docket No. TSMCP1120US

2020.2.18
Date

Chih-Yu Chang
Name 6th Inventor Chih-Yu Chang

TSMC Docket No. P20191274US00
Docket No. TSMCP1120US

2-19-2020
Date


Name 7th Inventor, Han-Jong Chia